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Sommario/riassunto

"Design for Excellence in Electronics Manufacturing offers comprehensive, up to date coverage specific to design and reliability of electronics. The book will highlight how utilizing the DfX concepts of Design for Reliability, Design for Manufacturability, Design for Environment, Design for Testability, etc., will not only reduce research and development costs, but will also decrease time to market and allow companies to confidently issue warranty coverage. Ultimately, Design for Excellence will increase customer satisfaction, market share, and long term profits. The Design for Excellence material is critical for engineers and management who wish to learn best practices regarding

		product design. Practices need to be adjusted for different manufacturing processes, suppliers, use environments, and reliability expectations, and this book will demonstrate how to do just that"--

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Sommario/riassunto	Annexed to GA Resolution 56/83 of 2001, the International Law Commission's Articles on Responsibility for Internationally Wrongful Acts put the international law of responsibility on a sound footing. As Special Rapporteur for the second reading, James Crawford helped

steer it to a successful conclusion. With this book, he provides a detailed analysis of the general law of international responsibility and the place of state responsibility in particular within that framework. It serves as a companion to The International Law Commission's Articles on State Responsibility: Introduction, Text and Commentaries (Cambridge University Press, 2002) and is essential reading for scholars and practitioners concerned with issues of international responsibility, whether they arise in interstate relations, in the context of arbitration or litigation, or in bringing international claims.